



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE8110ED	Issued	24. June 2021
MA#	MA002027398		
Package	PG-DSO-36-72	Weight*	540.21 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.286	2.27	2.27	22742	22742
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		134	
	non noble metal	iron	7439-89-6	0.241	0.04		447	
	non noble metal	copper	7440-50-8	240.973	44.61	44.66	446073	446654
wire	non noble metal	copper	7440-50-8	2.585	0.48	0.48	4784	4784
encapsulation	organic material	carbon black	1333-86-4	0.813	0.15		1505	
	plastics	epoxy resin	-	31.707	5.87		58693	
	inorganic material	silicondioxide	60676-86-0	238.478	44.15	50.17	441454	501652
leadfinish	non noble metal	tin	7440-31-5	6.656	1.23	1.23	12321	12321
plating	noble metal	silver	7440-22-4	3.599	0.67	0.67	6662	6662
glue	plastics	epoxy resin	-	0.490	0.09		907	
	noble metal	silver	7440-22-4	2.311	0.43	0.52	4278	5185
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com